RELIABILITY REPORT

FOR

MAX4081Xxxx+

PLASTIC ENCAPSULATED DEVICES

August 10, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX4081Xxxx+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX4080/MAX4081 are high-side, current-sense amplifiers with an input voltage range that extends from 4.5V to 76V making them ideal for telecom, automotive, backplane, and other systems where high-voltage current monitoring is critical. The MAX4080 is designed for unidirectional current-sense applications and the MAX4081 allows bidirectional current sensing. The MAX4081 single output pin continuously monitors the transition from charge to discharge and avoids the need for a separate polarity output. The MAX4081 requires an external reference to set the zero-current output level (VSENSE = 0V). The charging current is represented by an output voltage from VREF to VCC, while discharge current is given from VREF to GND. For maximum versatility, the 76V input voltage range applies independently to both supply voltage (VCC) and common-mode input voltage (VRS+). High-side current monitoring does not interfere with the ground path of the load being measured, making the MAX4080/MAX4081 particularly useful in a wide range of high-voltage systems. The combination of three gain versions (5V/V, 20V/V, 60V/V = F, T, S suffix) and a user-selectable, external sense resistor sets the full-scale current reading and its proportional output voltage. The MAX4080/MAX4081 offer a high level of integration, resulting in a simple, accurate, and compact current-sense solution. The MAX4080/MAX4081 operate from a 4.5V to 76V single supply and draw only 75µA of supply current. These devices are specified over the automotive operating temperature range (-40°C to +125°C) and are available in a space-saving 8-pin µMAX® or SO package.

II. Manufacturing Information

A. Description/Function:	76V, High-Side, Current-Sense Amplifiers with Voltage Output
B. Process:	BCD8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand, Malaysia
F. Date of Initial Production:	July 27, 2002

III. Packaging Information

A. Package Type:	8-pin uMAX
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-7001-0604
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	221°C/W
K. Single Layer Theta Jc:	41.9°C/W
L. Multi Layer Theta Ja:	206.3°C/W
M. Multi Layer Theta Jc:	41.9°C/W

IV. Die Information

A. Dimensions:	61 X 80 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 82 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.8 \times 10^{-9}$

$\lambda = 22.8$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the BCD88 Process results in a FIT Rate of 0.81 @ 25C and 14.05 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The OY07 die types have been found to have all pins able to withstand a HBM transient pulse of +/-1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250 mA.

Table 1
Reliability Evaluation Test Results

MAX4081Xxxx+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	47	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data